

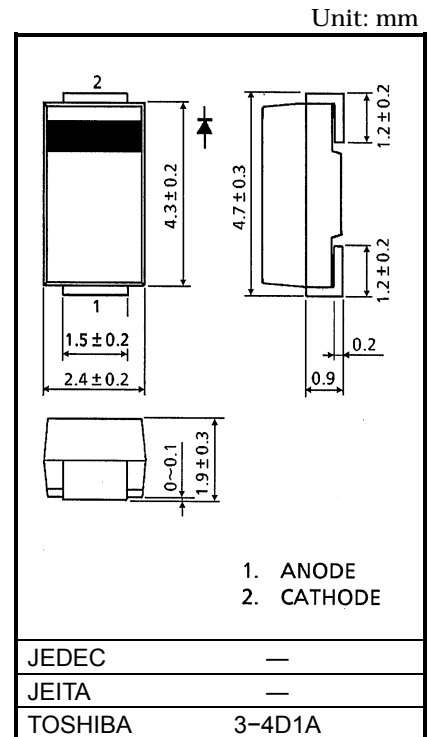
U2GWJ44

SWITCHING MODE POWER SUPPLY APPLICATION

- Low Forward Voltage : $V_{FM} = 0.55V$ (Max)
- Average Forward Current : $I_F (AV) = 2.0A$
- Repetitive Peak Reverse Voltage : $V_{RRM} = 40V$
- Surface Mounting Plastic Mold Package

MAXIMUM RATINGS ($T_a = 25^\circ C$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	V_{RRM}	40	V
Average Forward Current	$I_F (AV)$	2.0	A
Peak One Cycle Surge Forward Current (Non-Repetitive)	I_{FSM}	40 (50 Hz)	A
Junction Temperature	T_j	-40~125	$^\circ C$
Storage Temperature Range	T_{stg}	-40~125	$^\circ C$



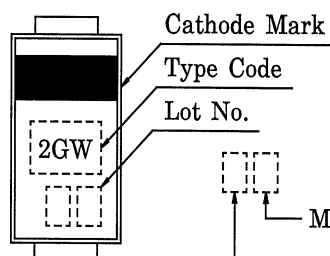
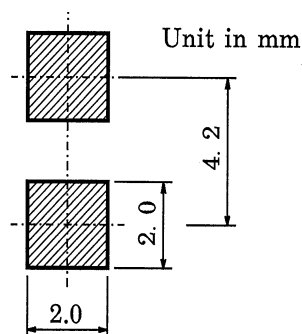
ELECTRICAL CHARACTERISTICS ($T_a = 25^\circ C$)

Weight: 0.06g

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Peak Forward Voltage	V_{FM}	$I_{FM} = 2.0A$	—	—	0.55	V
Repetitive Peak Reverse Current	I_{RRM}	$V_{RRM} = 40V$	—	—	500	μA
Junction Capacitance	C_j	$V_R = 10V, f = 1.0MHz$	—	125	—	pF
Thermal Resistance (Junction to Ambient)	$r_{th (j-a)}$	On ceramic substrate	—	—	60	$^\circ C / W$
		On glass-epoxy substrate	—	—	145	

STANDARD SOLDERING PAD

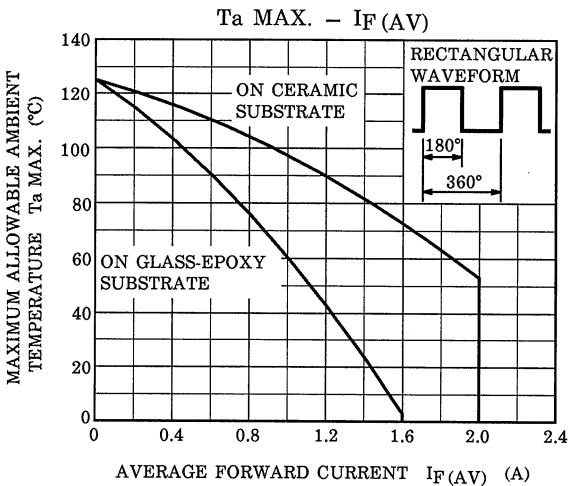
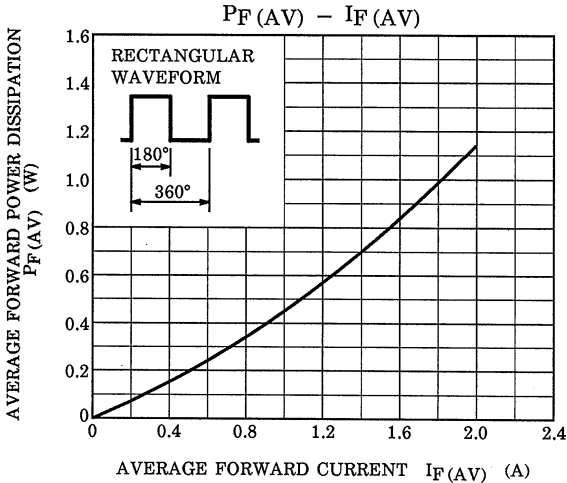
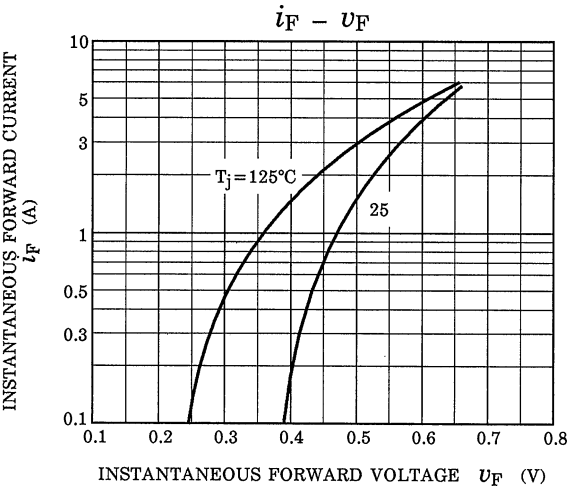
MARKING



Code	Type
2GW	U2GWJ44

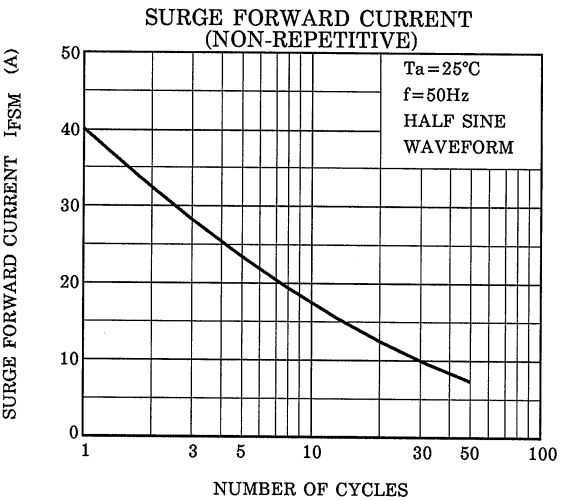
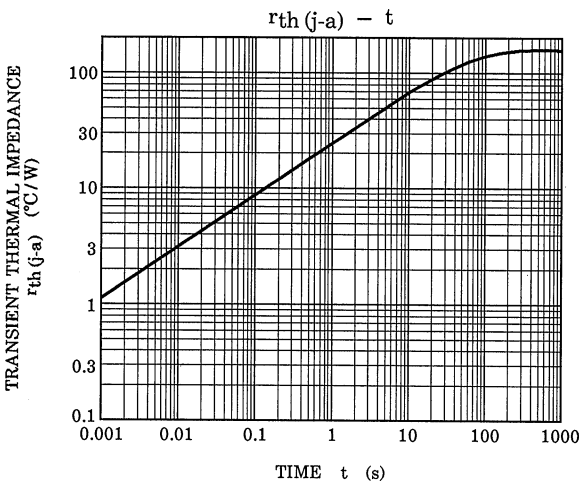
Month (Starting from Alphabet A)

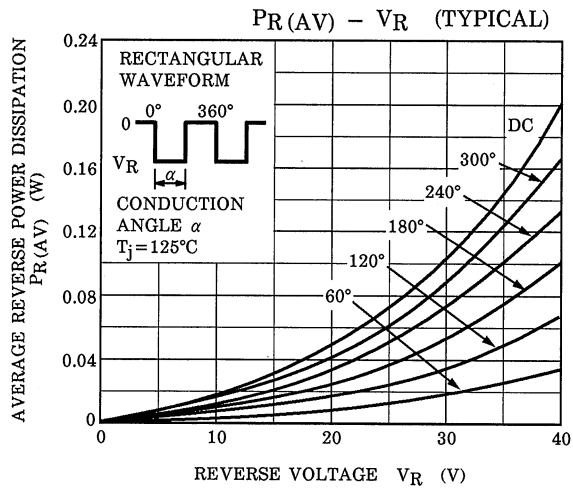
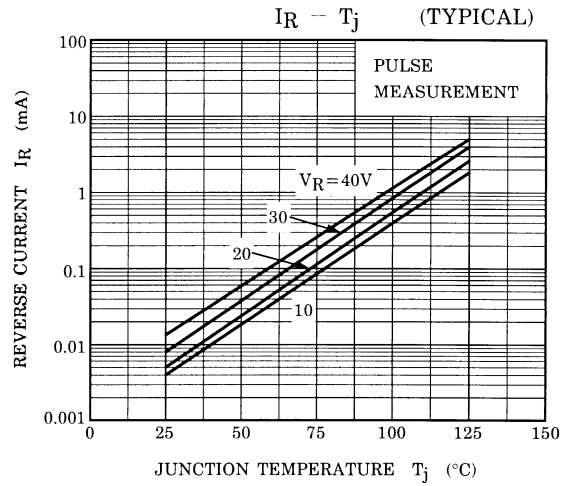
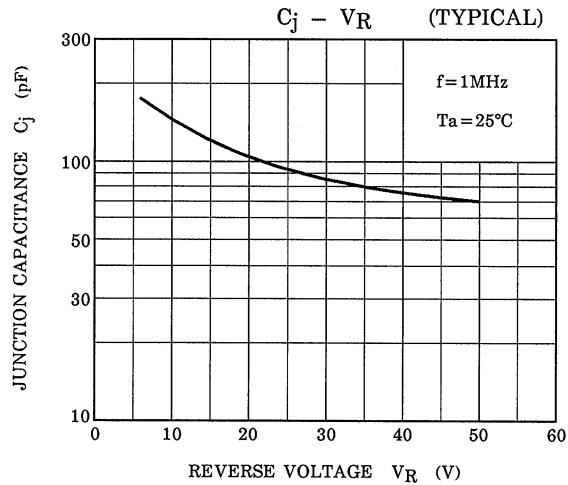
Year (Last Number of the Christian Era)



	ON CERAMIC SUBSTRATE	ON GLASS-EPOXY SUBSTRATE
Soldering land : a	2mm×2mm	6mm×6mm
Substrate size : b	50mm×50mm	50mm×50mm
Substrate thickness : c	0.64mm	1.6mm

The diagram shows a 3D perspective view of the device package. It is a rectangular block with a smaller rectangular soldering land on top. The dimensions are labeled: 'a' for the width of the soldering land, 'b' for the width of the substrate, and 'c' for the thickness of the substrate.





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